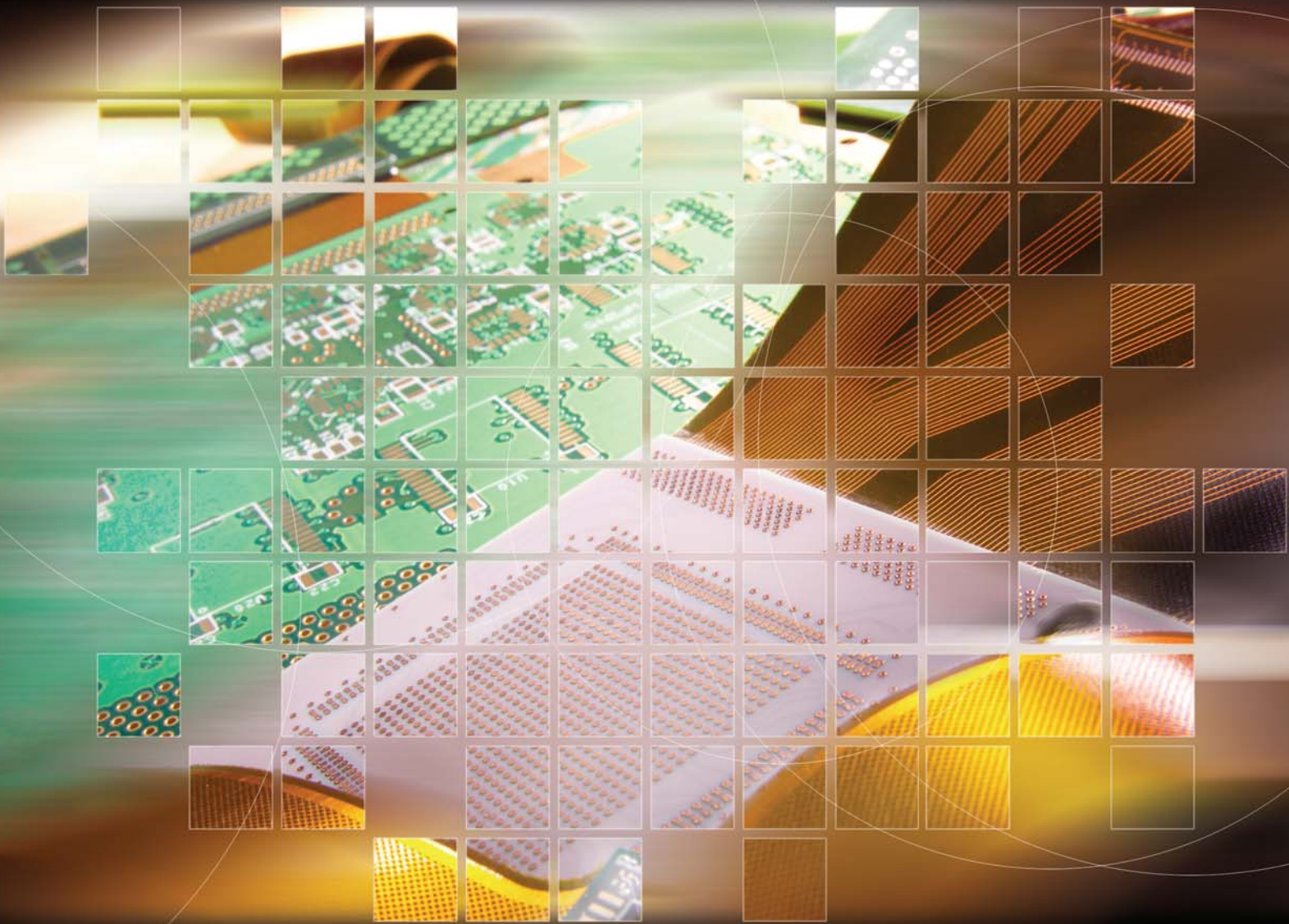


RIGID FLEX

HIGH LAYER COUNT • HIGH SPEED • HDI



More than a decade's experience in the design and manufacture of the highest quality rigid flex boards.

compunetics
excellence, measured in microns.

RIGID FLEX

Compunetics provides engineered solutions for the most complex rigid flex needs.

With design and manufacturing all under one roof, the Compunetics team is able to produce rigid flex boards of unparalleled quality and complexity. Compunetics' track record of innovation and strict attention to detail has made us the preferred choice of the most demanding clients.

Features include:

- Embedded resistor tolerance to $\pm 10\%$
- Thickness up to 20 layers
- Controlled impedance
- All-polyimide bond ply

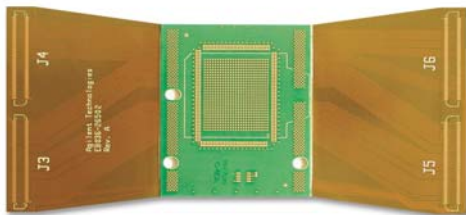
Applications include:

- Military
- Semiconductors
- Microprocessor testing
- Next generation silicon testing
- Supercomputing
- Aerospace
- Miniaturization
- Reliability enhancement

COMMERCIAL

Silicon Testing

Layers:	14 rigid; 3 flex
Material:	High Speed FR4 (Isola 408) Dupont AP Flex material
Trace Width:	0.002 +/- 0.0003" Controlled Impedance (64 ohms +/- 10%) Buried resistors (400 each of Ohmega 60 ohm +/- 10%) Buried capacitors (900 each)
Surface Finish:	Entec 106



Avionics

Layers:	8 'Looseleaf' Design
Finish:	3 Double-Sided Flex Cores with Coverlay 2-Ounce Copper on Flex Military Specification



MILITARY

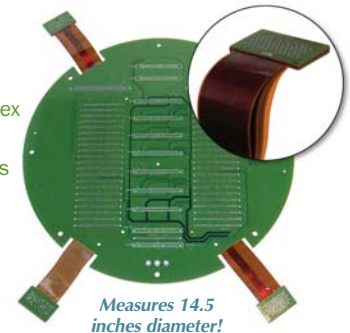
Ordinates Control

Layers:	10
Finish:	2-Ounce Copper Military Specification



Military

Layers:	22 'Looseleaf' Design
Material:	Polyimide Rigid DuPont AP Flex
Certifications:	Meets 50884 Specifications
Surface Finish:	HAL



Satellite Systems

Layers:	12
Trace/Space:	6/6 (150/150 μm)
Finish:	Immersion Gold
Material:	Polyimide Rigid DuPont AP Flex

